

Characterization of ITS upgrade prototype chips at Pusan

KyungEon Choi*, Jongsik Eum, Jiyoung Kim, In-Kwon Yoo

Pusan National University
Department of Physics
Busan, Republic of Korea

ITS-MFT and O² Asia Workshop @ Pusan
December 15, 2014



PUSAN NATIONAL UNIVERSITY



- ① Characterization of irradiated Explorer-1 chips with ^{55}Fe
- ② 60 MeV e^- test beam of irradiated Explorer-1 chips at Pohang
- ③ 60 MeV e^- test beam of pALPIDEfs chips at Pohang

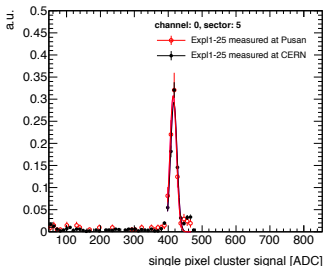
Reminder of previous workshop on June at Thailand

Milestones:

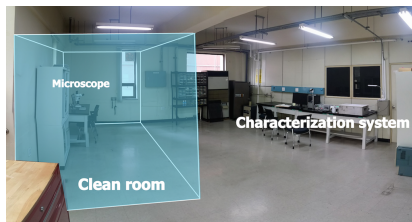
- Characterization system of Explorer-1 was fully commissioned.
- New lab space for mass test of chips and HIC assembly.
→ See Bong-Hwi's talk this afternoon.

Plan (characterization):

- Characterization of irradiated Explorer-1 chips with temperature control.
→ Chips were delivered on October.
- Start to work on pALPIDEfs characterization
→ Jongsik and myself visited CERN last August for a month.



[Comparison between Pusan and CERN data]



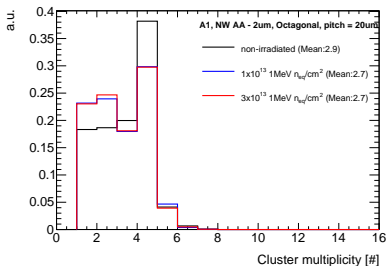
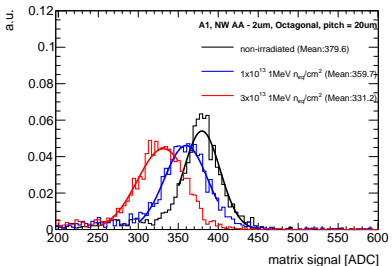
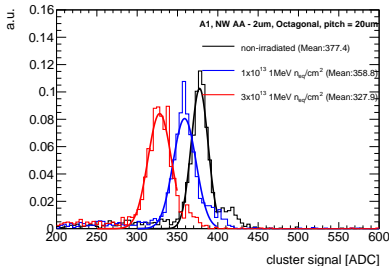
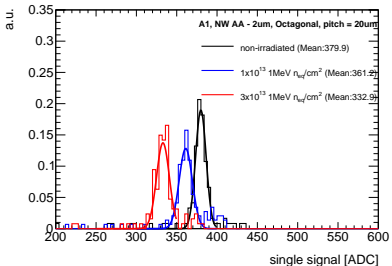
[New lab space for mass test and assembly]

Outline

- ① Characterization of irradiated Explorer-1 chips with ^{55}Fe
- ② 60 MeV e^- test beam of irradiated Explorer-1 chips at Pohang
- ③ 60 MeV e^- test beam of pALPIDEs chips at Pohang

Characterization of irradiated Explorer-1 chips with ^{55}Fe

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.

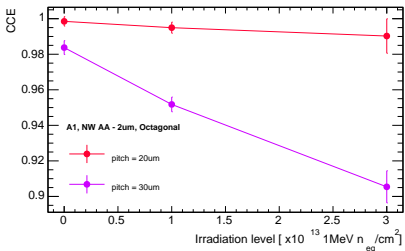


(** gain and cmc correction applied. Temperature = 30 $^{\circ}\text{C}$)

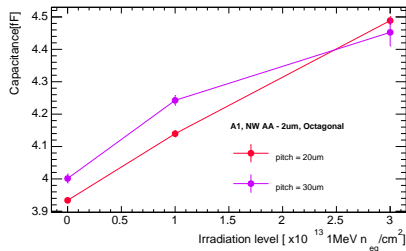
Comparison of 20 μm and 30 μm pixel pitch

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.

[CCE vs. irradiation level]



[Capacitance vs. irradiation level]



- Charge collection efficiency of 20 μm pitch stay almost 100% while 30 μm pitch decreases with irradiation level.
- Capacitance increases for both pixel pitches.

(** gain and cmc correction applied)

Outline

- ① Characterization of irradiated Explorer-1 chips with ^{55}Fe
- ② 60 MeV e^- test beam of irradiated Explorer-1 chips at Pohang
- ③ 60 MeV e^- test beam of pALPIDEs chips at Pohang

Introduction of Pohang Accelerator Lab

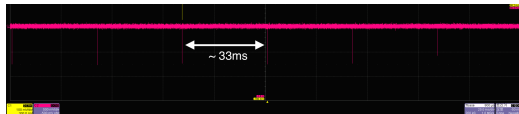
- Pohang Accelerator Laboratory (PAL) at Pohang (~ 2 hour drive from Pusan)
- Facilities
 - Light Source: 3 GeV electron Main LINAC + Storage ring
 - Test LINAC
 - 60 MeV e^- beam
 - $\sim \mu\text{s}$ bunch, 33 ms bunch space
 - Designed current $\sim \text{mA}$, **but can be tuned!**



[PAL bird's-eye view]



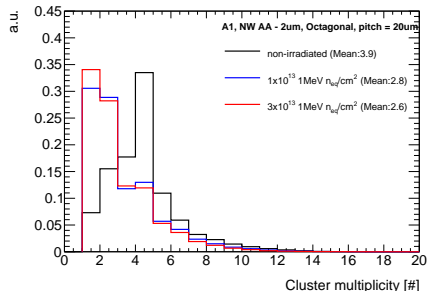
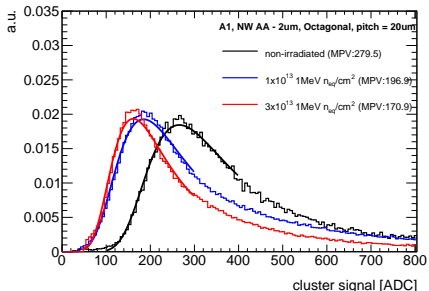
[Test LINAC]



[Trigger signal]

60 MeV e^- test beam of irradiated Explorer-1 chips

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.

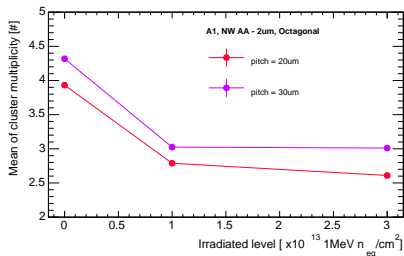
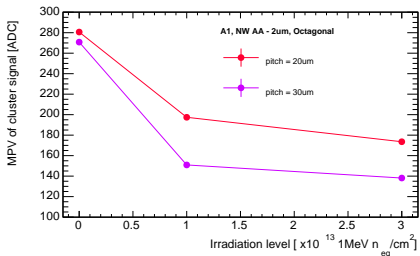


- Cluster signal (MPV) decreases about 30% after 1×10^{13} irradiation and about 40% after 3×10^{13} irradiation.
- Cluster multiplicity also decrease substantially and dominant multiplicity is changed from 4 to 1 or 2.
- Difference between 1 and 3×10^{13} irradiation is relatively small (needs further study, see backup).

(** gain and cmc correction applied)

Comparison of 20 μm and 30 μm pixel pitch

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.



- Irradiation effect on cluster signal size is more evident for 30 μm pixel pitch:
 $\sim 30\%$ drop for 20 μm and $\sim 45\%$ drop for 30 μm in case of 1×10^{13} irradiation level.

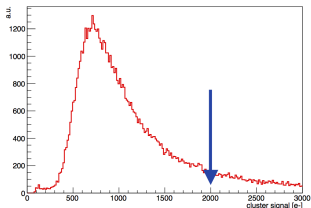
(** gain and cmc correction applied)

Outline

- ① Characterization of irradiated Explorer-1 chips with ^{55}Fe
- ② 60 MeV e^- test beam of irradiated Explorer-1 chips at Pohang
- ③ 60 MeV e^- test beam of pALPIDEs chips at Pohang

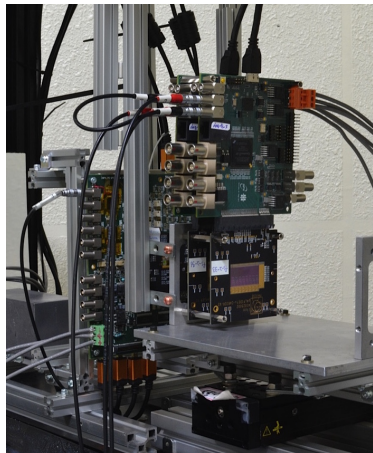
Threshold catastrophe of pALPIDEs on October

- Detector setup: **2 pALPIDEs layers**
- Maximum occupancy of each chip was limited to 400 hits per event.
- Due to very high beam intensity, possible threshold range for the measurement: **2000 ~ 2800 electrons**
→ Very high threshold!



[cluster signal on Explorer-1]

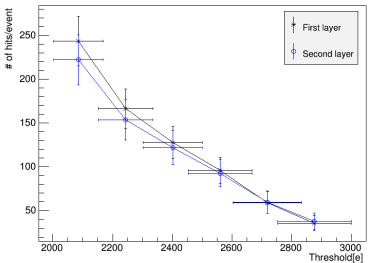
- No hit from noise for these thresholds.
- **Therefore, very hard to see X and Y position correlation between two pALPIDEs planes, but we still can see electrons who deposit large energy.**



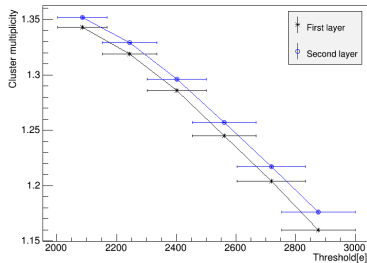
[Detector layout at beamline]

Basic plots

[Number of hits per event vs. threshold]



[Cluster multiplicity vs. threshold]

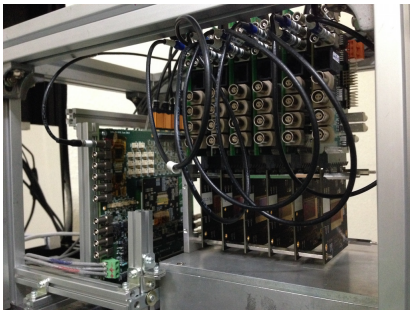


- Number of hits (or pixels) per event and cluster multiplicity decreases as a function of threshold.
- More than 200 hits with lowest threshold and we could expect more than 400 hits with one step lower threshold.
- Although we weren't able to measure with nominal threshold range to see correlations, pALPIDEfs chips behaved functionally under harsh condition.

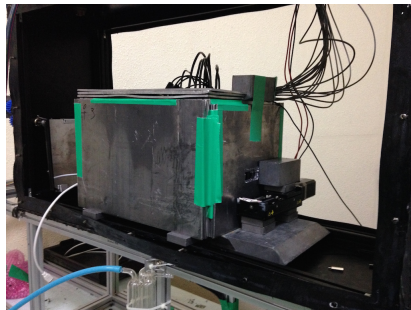
Test beam on December

Main updates from October test beam:

- 1 Reduction of beam intensity dramatically \sim factor 50
- 2 6 pALPIDEfs layers (4 pALPIDEfs layers are added) to reconstruct tracks.



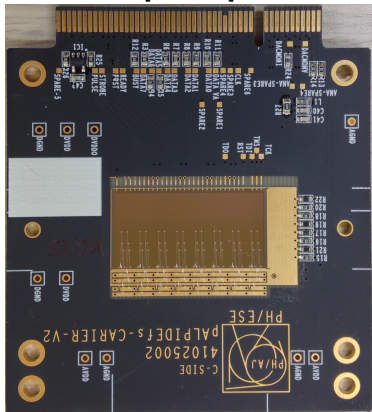
[Detector layout at beamline]



[Before turn beam on]

Before plots from pALPIDEs chips

[Front]

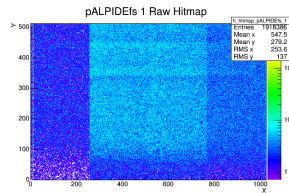
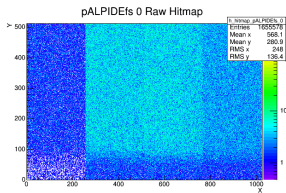


[Back]



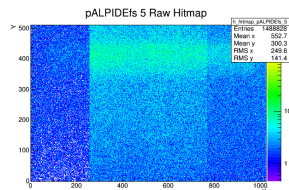
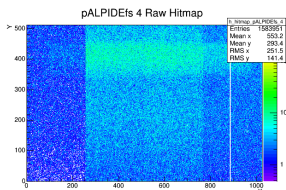
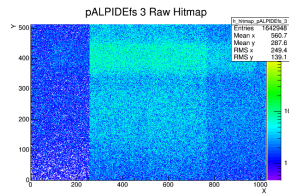
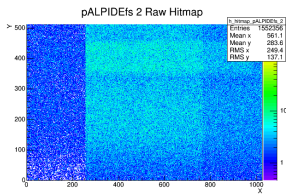
- pALPIDEs chip is mounted on the carrier board (PCB ~ 2mm thick)
- Large fraction of chip is overlapped with the carrier board (PCB) except long window.
→ **No material after 50 μm thick chip itself**

Hit map of 6 pALPIDEs planes



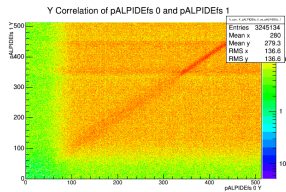
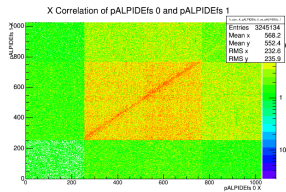
[Layout]

Layer 1	Layer 2
Layer 3	Layer 4
Layer 5	Layer 6

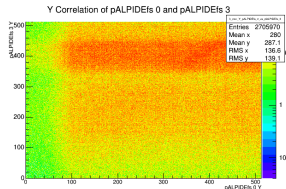
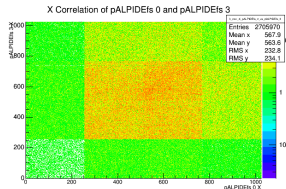
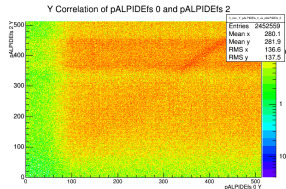
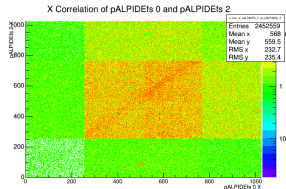
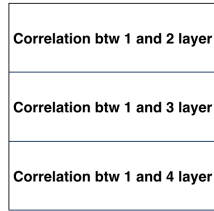


- Threshold settings ~ 150 electrons.
- Hit map of 1st layer is very uniform within each sector (4 sectors can be distinguished via vertical lines). Less hits at bottom caused by collimator.
- Electrons experience multiple-scattering or are absorbed by PCBs underneath pALPIDEs chips.

X and Y correlations btw 1st and other pALPIDEs planes

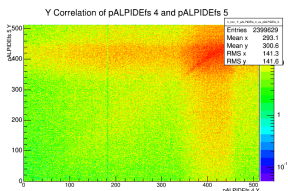
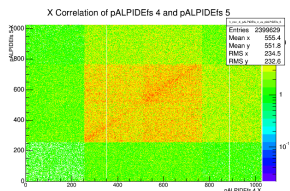
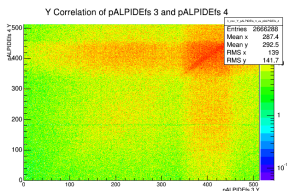
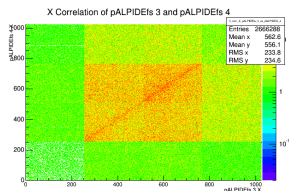
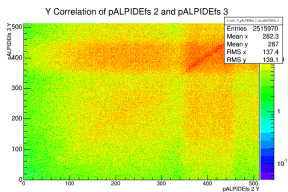
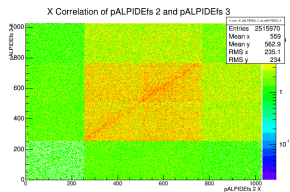


[Layout]



- Clear X position correlation between 1st and 2nd layers especially efficient middle 2 sectors.
- Y position correlation is basically visible and clear only hole area of carrier board.
- Correlations are getting faint as we correlate farther layers.

X and Y correlations btw pALPIDEs planes



[Layout]

Correlation btw 3 and 4 layer
Correlation btw 4 and 5 layer
Correlation btw 5 and 6 layer

- It's always possible to see correlations between two neighboring pALPIDEs planes though it gets more background from scattered electrons.

Summary & Outlook

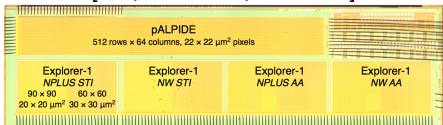
- There are many ongoing activities at Pusan for pixel chip characterization.
- Explorer-1:
 - Measurement of irradiated chips with ^{55}Fe is ongoing and many more analyses can be done.
 - Test beam data of irradiated chips will be further analyzed then write a documentation together with ^{55}Fe data.
- pALPIDEfs characterization:
 - We were able to tune the beam to reach enough low intensity for pALPIDEfs measurements.
 - Low energy electrons (60 MeV) scatter a lot at carrier boards (PCB).
 - Electrons pass through the holes in the carrier board look promising.
- Jongsik will be at CERN from January 19th to February 13th, 2015 for the detail analysis of pALPIDEfs data based on Eutelescope.

Backup

ALPIDE prototypes (CERN)

- 1 **Explorer**: analog output, pixel sensor optimization - diode geometry, epitaxial layer thickness, back bias, etc.
- 2 **pALPIDEs**: binary output, circuit optimization
- 3 **pALPIDEfs**: binary output, full scale prototype for system studies
- 4 **Investigator**: analog output, pixel sensor optimization - pixel size, input transistor location, etc.

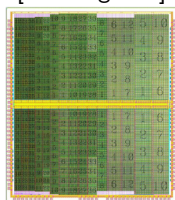
[Explorer and pALPIDE]



dimension: 3.6×1.8 mm (per Explorer-1)

#pixels: 2k (per Explorer-1)

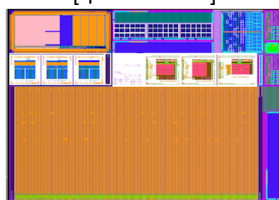
[Investigator]



5.0×5.8 mm

#pixels: 8k

[pALPIDEfs]

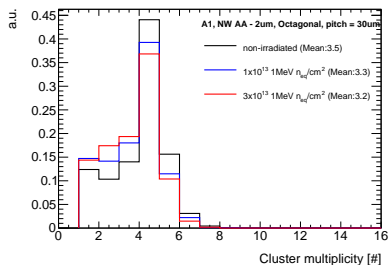
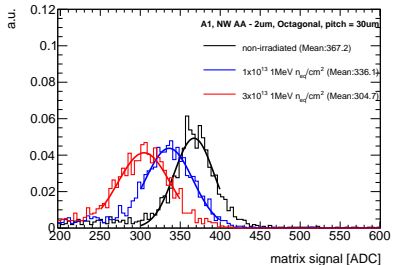
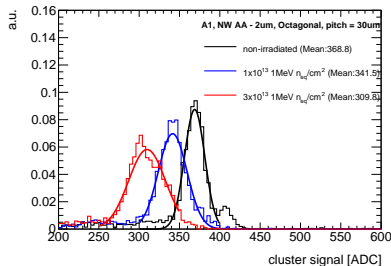
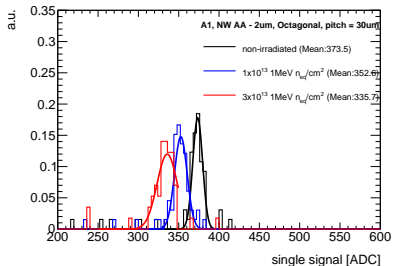


15×30 mm

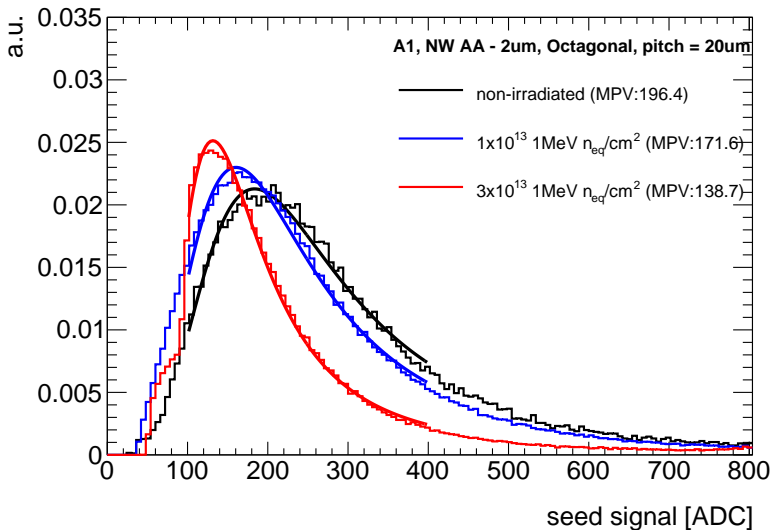
#pixels: 524k

Characterization of irradiated Explorer-1 chips with ^{55}Fe

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.

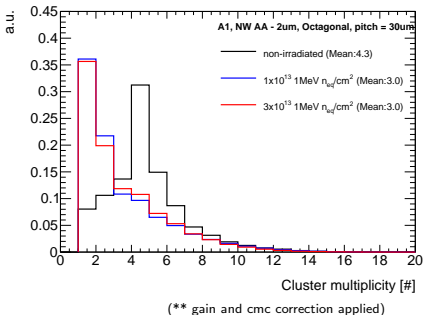
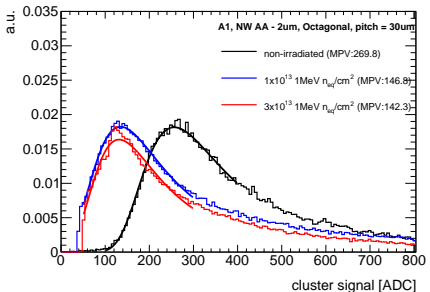


Deformation of seed distribution after irradiation



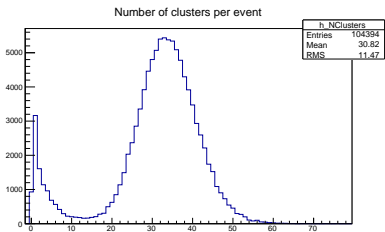
60 MeV e^- test beam of irradiated Explorer-1 chips

- 18 μm epitaxial layer thickness, 1k Ωcm resistivity, -6 V reverse bias voltage.

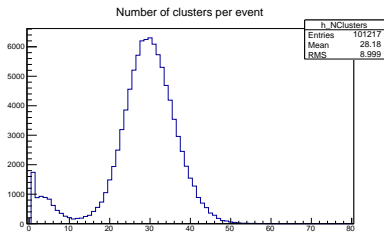


Naive estimation of beam intensity via Explorer-1

- Assume Explorer-1 is fully efficient at back bias = -6V.
- Average number of clusters in Explorer-1 ~ 60 clusters (or electrons).
- Active area of pALPIDEs/Explorer-1 ~ 20 .
- ~ 1800 electrons on pALPIDEs if beam is uniform.
- ~ 2700 hits (or pixels) on pALPIDEs (if, cluster multiplicity = 1.5)
- pALPIDEs cannot measure all these particles, moreover we cannot have clean reconstructed tracks from 2700 hits.

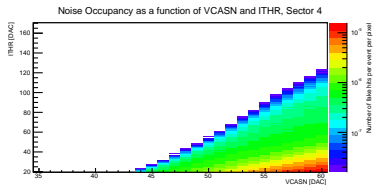
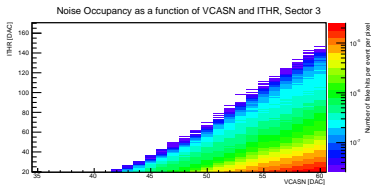
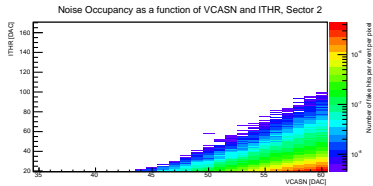
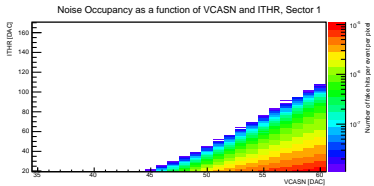


[$20 \times 20 \mu\text{m}^2$]

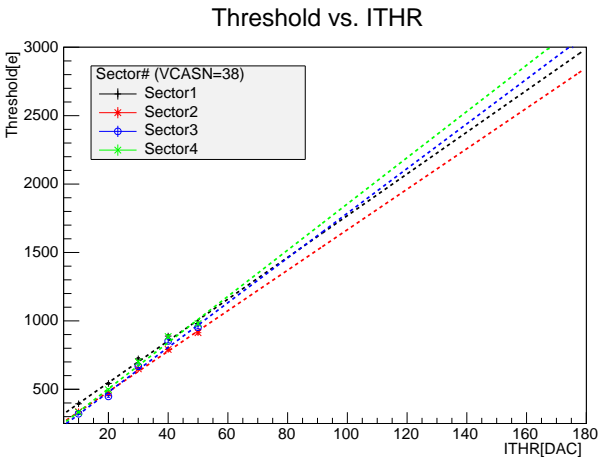


[$30 \times 30 \mu\text{m}^2$]

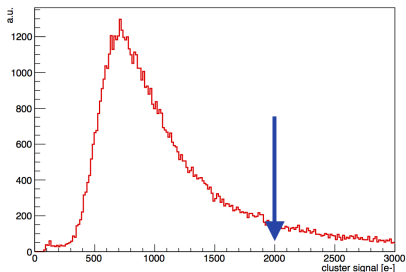
Noise occupancy



Threshold extraction



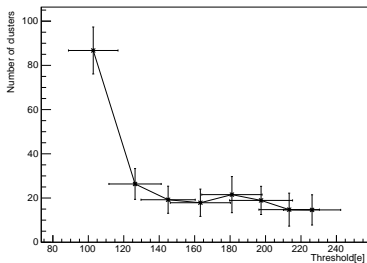
Some useful information from Explorer-1



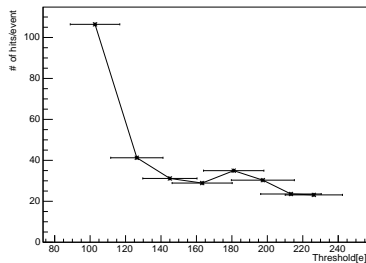
- Cluster signal of Explorer-1 ($20 \times 20 \mu\text{m}^2$ pixel, $2 \mu\text{m}$ octagonal n-well and STI) at back bias voltage = -6V from 60 MeV electron.
- Calibrated with ^{55}Fe source \rightarrow x-axis in electrons.
- Small fraction ($\sim 9\%$) of electrons deposit enough energy to generate more than 2000 electrons.
- **Therefore, very hard to see X and Y position correlation between two pALPIDEs planes, but we still can see electrons with large energy deposit.**
- **No X and Y position correlation between two planes means we cannot reconstruct track!**

Basic plot of DUT on December

[Cluster multiplicity vs. threshold]



[Number of hits per event vs. threshold]



Hits vs. Plane

